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L1: Entry 64 of 64

File: DWPI

Jul 31, 1978

DERWENT-ACC-NO: 1978-61551A

DERWENT-WEEK: 197834

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TITLE: Photomask cleaning - used to remove photoresist from e.g. metal or glass film
used in semiconductor integrated circuit mfr.

PATENT-ASSIGNEE: TOKYO SHIBAURA ELECTRIC CO (TOKE)

PRIORITY-DATA: 1976JP-0103576 (September 1, 1976)

PATENT-FAMILY:

PUB-NO	PUB-DATE	LANGUAGE	PAGES	MAIN-IPC
JP 78026112 B	July 31, 1978		000	
JP 53029671 A	March 20, 1978		000	

prior?

INT-CL (IPC): H01L 21/30

ABSTRACTED-PUB-NO: JP78026112B

BASIC-ABSTRACT:

Photomask adhered with photoresist, etc. is cleaned by the chemical reaction of the photoresist, etc. and activated gas in a reaction chamber by ELAM (Etching Technology using Long Life Active Species Excited Microwave) process. Damage to the substrate is prevented.

ABSTRACTED-PUB-NO: JP78026112B

EQUIVALENT-ABSTRACTS:

DERWENT-CLASS: G06 L03 U11 U12

CPI-CODES: G06-D06; G06-E; L03-D03;

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L1: Entry 40 of 64

File: JPAB

Jul 21, 1984

OK

DOCUMENT-IDENTIFIER: JP359126630 A

TITLE: METHOD AND DEVICE FOR CORRECTING PHOTOMASK

Abstract (1):

PURPOSE: To prevent the contamination of a photomask by a method wherein, before the photomask is taken out into the atmospheric air, the organic metal solution adhered to the photomask is removed using a cleaning solvent.

Abstract (2):

CONSTITUTION: The laser beam sent from a laser oscillator 1 is condensed and irradiated on the perforated defective part of a photomask 4 by a condensing lens 3 through the intermediary of a reflecting mirror 2. The illumination light sent from an illumination light source 5 is overlapped on the laser beam through the intermediary of a beam splitter 6, and an observation is performed by the observing optical system 7 of the photomask 4. An organic metal solution is filed in a holder 8 from a raw solution reservoir 9, a laser beam is made to irradiated in a converged form on the defective part of the photomask, and the organic metal which is dissociated from the solution is deposited on the perforated defective part. After the defective part has been corrected, a cleaning solvent such as toluene and the like flows into the holder 8 from a cleaning solvent reservoir 16, and the organic metal solvent is washed away from the surface of the photomask 4, thereby enabling to prevent the contamination of the photomask due to the oxidation of the organic metal.